

Title (en)

METHOD FOR PRODUCING AN ELECTRONIC COMPONENT AND ELECTRONIC COMPONENT

Title (de)

VERFAHREN ZUM HERSTELLEN EINES ELEKTRONISCHEN BAUSTEINS UND ELEKTRONISCHER BAUSTEIN

Title (fr)

PROCÉDÉ DE FABRICATION D'UN MODULE ÉLECTRONIQUE ET MODULE ÉLECTRONIQUE

Publication

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Application

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Priority

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- DE 102007035902 A 20070731

Abstract (en)

[origin: WO2009016041A1] The invention relates to a method for producing an electronic component (100), wherein a plurality of chips (3) disposed in a wafer on a passivated main side having at least one chip contact surface (4, 5) is provided with an insulation layer (7). The insulation layer (7) has openings (12) in the area of the at least one chip contact surface (4, 5) of each chip (3). The chip contact surfaces (4, 5) of each chip (3) are provided with a chip contact surface metallization (8, 9) of a prescribed thickness, and the chips disposed in the wafer (3) are separated therefrom.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2009016041A1

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